

DERWENT-ACC-NO: 2003-742114

DERWENT-WEEK: 200370

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TITLE: Ball grid array type stacked package

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PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE
PAGES MAIN-IPC		
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APPLICATION-DATA:

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INT-CL (IPC): H01L023/12

ABSTRACTED-PUB-NO: KR2003047403A

BASIC-ABSTRACT:

NOVELTY - A ball grid array type stacked package is provided to be capable of increasing the number of pins by arranging solder balls on the bottommost surface of the stacked package as an outer connection terminal.

DETAILED DESCRIPTION - Semiconductor chips(21,41) having a plurality of bonding pads(27a,47a) are mounted on substrates(25,45), respectively. At this time, the substrates include metal lines(27,28,47,48). Protruded leads(31,51) are attached to the metal lines(27,47) at the edge portions of the substrates. Bonding wires(33,53) are electrically connected between the semiconductor chips

and the leads. The upper portions of the resultant structures are enclosed by molding parts(35,55). At this time, a plurality of unit semiconductor chip packages(20,40) are completely formed. Then, a ball grid array type stacked package(10) is formed by stacking one unit semiconductor chip package(20) on the other unit semiconductor chip package(40) by attaching between leads(31,51). A plurality of solder balls(57) are formed and attached on the rear surface of the substrate(45).

CHOSEN-DRAWING: Dwg.1/10

TITLE-TERMS: BALL GRID ARRAY TYPE STACK PACKAGE

DERWENT-CLASS: U11 V04

EPI-CODES: U11-D03; V04-R04A;

